

Thermally conductive adhesive

- solvent-free and thermal conductive two part adhesive
- epoxy based filled with aluminium oxide
- composition of hardener and resin (1:1) with statical mixing tube
- lockability of the container via Luer-Lock System
- good usage and working properties

WLK DK 4



WLK DK 10



WLK DK 50



art. no.	basin	contents of delivery
WLK DK 4	syringe	1x 4 ml syringe / 3x mixer WLK M4
WLK DK 10	syringe	1x 10 ml syringe / 3x mixer WLK M4
WLK DK 50	cartridge	1x 50 ml cartridge / 3x mixer WLK M50

WLK DK

thermal conductivity	1 W/m·K
specific thermal resistance	118°C cm/W
volume resistance	8·10 ¹¹ Ω/cm
temperature range	-50°C... +145°C
working life at room temperature	approx. 30 min
hardening time	25°C approx. 4 h/50°C approx. 1 h/85°C approx. 10 min/125°C approx. 2 min
glue layer	Epoxid
mixture proportion	1:1

Accessories

- more package sizes and container types upon request
- store cool and dry

art. no.	contents of delivery
WLK M 4	10x mixer für 4 & 10 ml syringe (packing unit 10 pieces)
WLK M 50	10x mixer für 50 ml cartridge (packing unit 10 pieces)
WLK P	1x applicator gun for 50 ml cartridge

Thermal conductive material
Thermal conductive foil
GEL thermal conductive foils
Thermal conductive paste

→ E 2 - 5
 → E 7 - 10
 → E 12 - 15
 → E 21 - 22

Thermal conductive glue
 fan cooler for Pentium and MMX
 heatsinks for Pentium III FC PGA
 Technical introduction

→ E 23 - 24
 → B 59
 → B 57
 → A 2 - 8

E 24